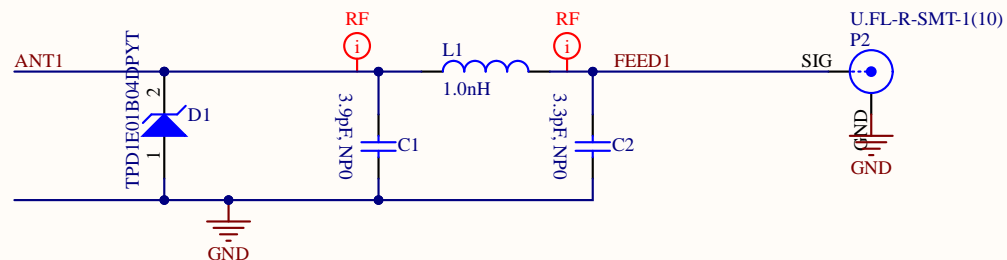


A

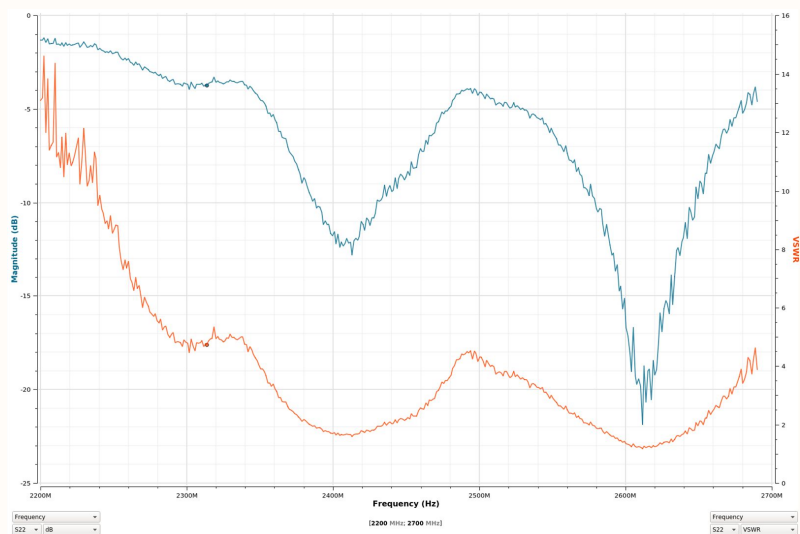
A

PIFA antenna

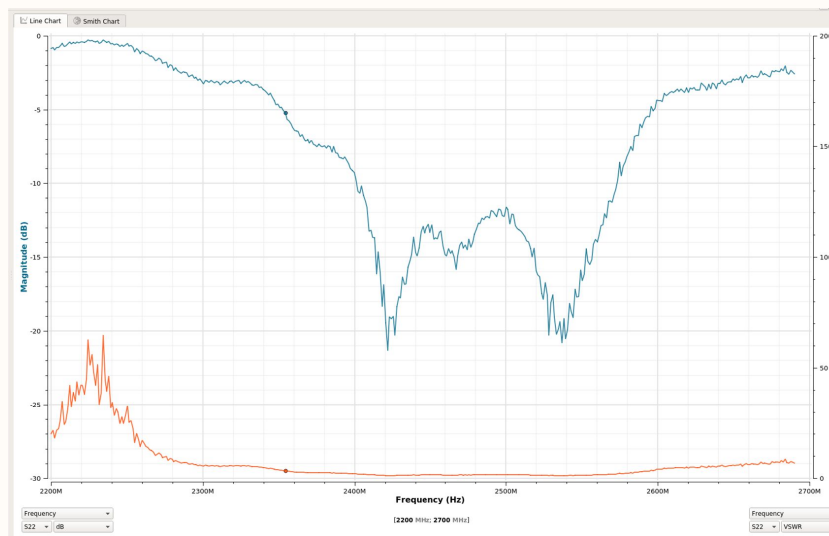


B

B



3.3-1.0-3.3



3.9-1.0-3.3

C

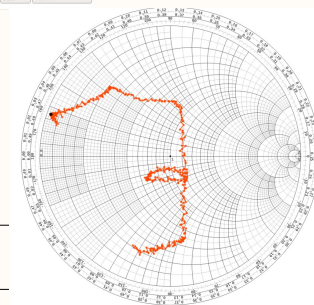
C

D

D

<https://home.sandiego.edu/~ekim/e194rfs01/jwmatcher/matcher2.html>

Title	
Size	Number
A	
Date:	12/01/2021
File:	F:\largework\...\connectors.SchDoc



Sheet of
Drawn By:

Profile of cross section line C-C, showing countersink hole and back mill

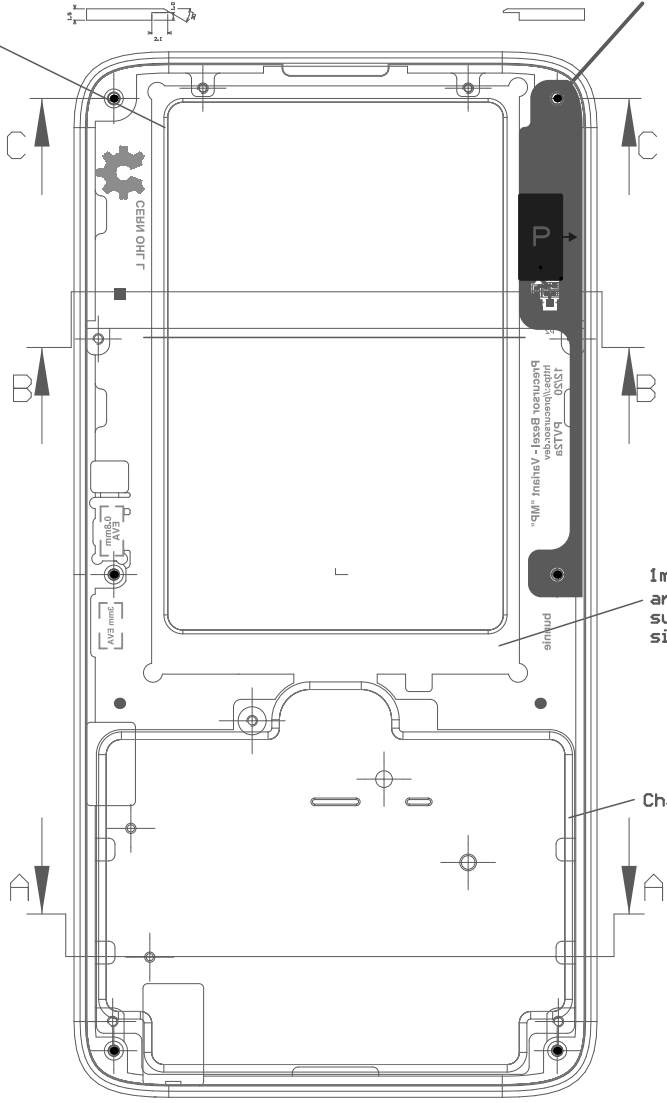


Profile of cross section line B-B, showing 30 degree chamfer from top and 1mm back-mill



Note: 6x countersink hole 45 degree, see section C-C

Chamfer 30 degree / 0.5mm from top side



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Layer		0.036mm		
	Light blocking FR-4	FR-4	1.500mm	4.8	
2	Bottom Layer		0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				

Finish: immersion gold
Top side no solder mask or silkscreen
Bottom side clear soldermask, light gray silkscreen
Please see .GM1 and .GM2 for chamfer and step-milling instructions



Profile of cross section line A-A, showing 15 degree chamfer from top + 1mm back-mill